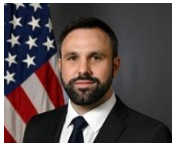
ASU Southwest Advanced Prototyping Hub
Arizona State University



Annual Meeting & Advanced Packaging Workshop

October 26 to 28, 2026
Mountain America Stadium, ASU, Tempe, AZ

Keynote Speakers



Mr. Eric Makara
OUSW (R&E)
OASW (CT)



Dr. Nicholas Martin
Director of the Defense Microelectronics Activity (DMEA)



Mr. Tim Olson
Founder & CEO' of Deca Technologies

DoW Perspective Invited Talks



Dr. Michael Sinanis
NSWC Crane, OASW, IBAS RESHAPE



Dr. Kelson Chabak
AFRL, Microelectronics Technical Area Lead



Dr. Brian Olson
NSWC, OUSW (R&E) SHIP Program Lead

Engaging Fireside Chats & Panel Discussions



Ms. Lisa Depew
Intel, Program Director, Corporate University Research



Mr. David McCann
Amkor Technology
Sr VP, Chief of Staff



Dr. Dev Palmer
Applied Research Institute Consultant



Dr. Michael Holmes
DARPA Managing Director NGMM



Dr. Ravi Mahajan
Intel, Fellow, Assembly & Test Tech Pathfinding



Mr. Drew Trojanowski
Southwest Mission Acceleration Center, CEO

DAY 1

- Drive Future Business & Sustainability
- Highlights of Technical Achievements
- Venture Capital Panel
- Exhibitor Reception

DAY 2

- DoW Leadership Keynote Speakers
- Hub Partner Capabilities Presentations
- Connecting Challenges to Practical Solutions
- MacroTechnology Works Tour and Reception

DAY 3

- DoW Leadership Keynote Speakers
- Open Forum and Discussion Panels
- FOWLP Advanced Packaging Updates

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